

Product Change Notification - BCD2000005 - JAON-22ZKEM744

Date: 14 Oct 2016
Product Category: Micrel
Notification subject: CCB 1737.02 Final Notice: Release to production of listed Micrel Power Switch product type manufactured with the BCD2 process technology to Microchip Fab.
Notification text: **PCN Status:**
 Final Notification

Note: This final PCN only pertains to the products listed in this PCN. Additional final PCNs may be issued for this combination of product type and process technology.

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Release to production of listed Micrel Power Switch product type manufactured with the BCD2 process technology to Microchip Fab.

NOTE: Please review the FAQ linked [here](#) for additional information about this change.

Pre Change:

Fabricated at Micrel fabrication site (San Jose, CA, USA) using 6 inch wafers.

Post Change:

Fabricated at Microchip fabrication site using 8 inch wafers.

Pre and Post Change Summary:

	Pre Change	Post Change
Fab Site	Micrel fabrication site (San Jose, CA, USA)	Microchip fabrication site
Wafer Size	6 inch wafers	8 inch wafers

Impacts to Data Sheet:

None

Reason for Change:

To improve productivity with the closure of the Micrel fab as part of the integration of Micrel and Microchip.

Change Implementation Status:

In Progress

Estimated First Ship Date:

As identified for each CPN listed in the attached parts list.

Summary Time Table of notable events to date:

	September 2015					->	February 2016				->	October 2016				November 2016			
Workweek	36	37	38	39	40		05	06	07	08		40	41	42	43	44	45	46	47
Initial PCN Issue Date	X																		
CYER-31JLEX869																			

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Affected Catalog Part Numbers (CPN)

PCN_JAON-22ZKEM744-BCD2000005	
CATALOG_PART_NBR	Estimated First Ship Date (EFSD)
MIC2026-2YM	November 25, 2016
MIC2026-2YM-TR	October 28, 2016
MIC2027-2YM	November 25, 2016
MIC2027-2YM-TR	November 25, 2016
MIC2027-2YWM	November 25, 2016
MIC2027-2YWM-TR	November 25, 2016
MIC2073-2YM	November 25, 2016
MIC2073-2YM-TR	November 25, 2016
MIC2074-2YM	November 25, 2016
MIC2074-2YM-TR	November 25, 2016
MIC2076-2YM	November 25, 2016
MIC2076-2YM-TR	November 25, 2016
MIC2077-2YM	November 25, 2016
MIC2077-2YM-TR	November 25, 2016
MIC2077-2YWM	November 25, 2016
MIC2077-2YWM-TR	November 25, 2016



MICROCHIP

QUALIFICATION REPORT
RELIABILITY LABORATORY

PCN #: JAON-22ZKEM744

Date
February 8, 2016

**Qualification of Microchip 8 inch Fabrication site for Micrel products
manufactured with the BCD2 Process Technology.**

PART NUMBER	PACKAGE TYPE	ASSEMBLY LOCATION	WAFER SIZE	PROCESS NAME
MIC2026-1YM /238A0/1	SOIC-8L	STARS, THAILAND	8"	BCD2

DIE QUALIFICATION RESULTS

TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	168 HR Rej/ss	500 HR Rej/ss	1000 HR Rej/ss	COMMENTS
HTOL High Temperature Operating Life Test	JESD22, Method 108	1542	V216.195868.000MQA	0/77	0/77	0/77	
	TA= + 125°C	1543	V216.195868.100MQA	0/77	0/77	0/77	
	VCC = 5.5V	1545	V216.216184.100MQA	0/77	0/77	0/77	

ELECTROSTATIC DISCHARGE

TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	STRESS	RESULT Rej/ss	COMMENTS
ESD-HBM Human Body Model ATE Test @ Room +25C	R= 1500 Ohms C= 100 pF 1X +/- Voltage	1542	V216.195868.000MQA	+/-2000V	0/3	Note: ESD ratings are device specific. All Products qualified on the 8" Micrel process technologies will have the same or better ESD and Latch-up performance as the 6" San Jose Products.
ESD-CDM Charged Device Model ATE Test @ Room +25C	JESD22-C101 1X +/- Voltage	1542	V216.195868.000MQA	+/-1500V	0/3	
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	STRESS	RESULT Rej/ss	COMMENTS
LATCH-UP	JESD-78	1542	V216.195868.000MQA	I/O LU	0/6	
	TA = +25°C			O/V LU	0/6	

PACKAGE QUALIFICATION RESULTS					
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	Rej/ss	COMMENTS
Level 1 Pre-conditioning Flow	JESD22-A113	1542	V216.195868.000MQA	0/321	
		1543	V216.195868.100MQA	0/143	
		1545	V216.216184.100MQA	0/145	
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	96 HR Rej/ss	COMMENTS
PRESSURE POT With Level 1 Pre- conditioning Tpeak + 260°C 3X Reflow	JESD22-A102 Ta = +121°C/100%RH 15 PSIG	1542	V216.195868.000MQA	0/45	
		1543	V216.195868.100MQA	0/45	
		1545	V216.216184.100MQA	0/45	
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	96 HR Rej/ss	COMMENTS
HAST With Level 1 Pre- conditioning Tpeak + 260°C 3X Reflow	JESD22-A110 (BIASED) Ta= +130°C/85%RH JESD22-A118 (UNBIASED)	1542	V216.195868.000MQA	0/45	
		1543	V216.195868.100MQA	0/45	
		1545	V216.216184.100MQA	0/45	
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	500 CY Rej/ss	COMMENTS
TEMP CYCLE With Level 1 Pre- conditioning Tpeak + 260°C 3X Reflow	JESD22-A104 Ta = -65°C / +150°C	1542	V216.195868.000MQA	0/45	
		1543	V216.195868.100MQA	0/45	
		1545	V216.216184.100MQA	0/45	
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	1000 HR Rej/ss	COMMENTS
HTSL High Temperature Storage Life With Level 1 Pre- conditioning	JESD22-A103 Ta = +150°C	1542	V216.195868.000MQA	0/76	
		1542	V216.195868.000MQA	0/76	
HTSL High Temperature Storage Life With Level 1 Pre- conditioning	JESD22-A103 Ta = +175°C	1542	V216.195868.000MQA	0/76	
		1542	V216.195868.000MQA	0/76	
FLAMMABILITY	UL-94V-0 Certified	All mold compounds used by Micrel meet this standard. See the UL website on-line list of material flammability certifications. Micrel requires a Certificate of Compliance from the assembly house and we verify the certifications on the web.			